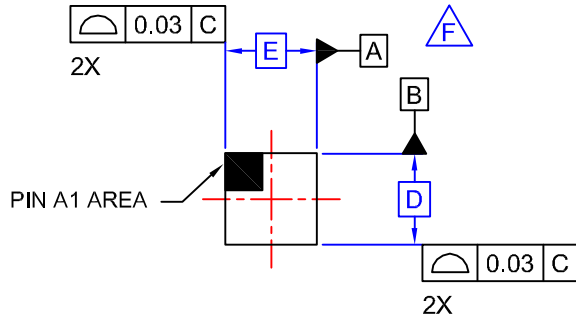
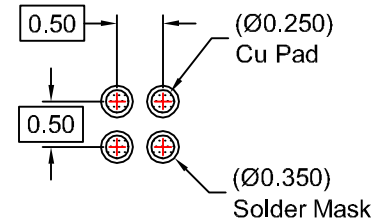


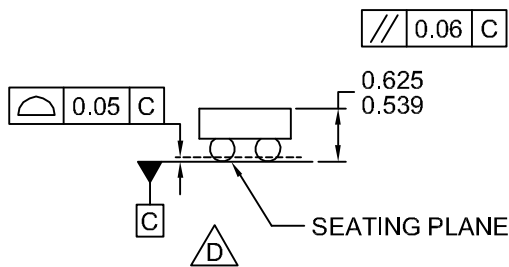
REVISIONS			
REV	DESCRIPTION	DATE	APP'D / SITE
1	Initial drawing release.	11-6-07	L. England / FSME
2	Corrected bump dimension number. Other general updates for drawing standardization.	9-28-09	L. England / FSME



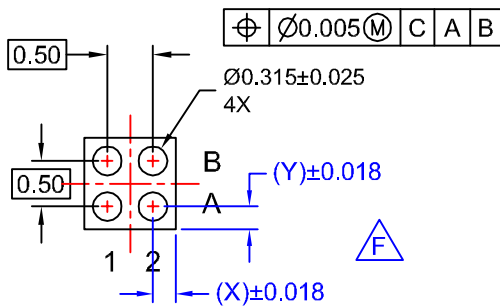
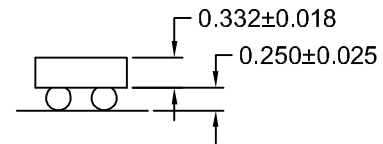
TOP VIEW



RECOMMENDED LAND PATTERN
(NSMD PAD TYPE)



SIDE VIEWS



BOTTOM VIEW

NOTES:

A. NO JEDEC REGISTRATION APPLIES.

B. DIMENSIONS ARE IN MILLIMETERS.

C. DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 1994.

D. DATUM C IS DEFINED BY THE SPHERICAL CROWNS OF THE BALLS.

E. PACKAGE NOMINAL HEIGHT IS 582 MICRONS ±43 MICRONS (539-625 MICRONS).

F. FOR DIMENSIONS D, E, X, AND Y SEE PRODUCT DATASHEET.

G. DRAWING FILENAME: MKT-UC004ABrev2.

APPROVALS		DATE	FAIRCHILD SEMICONDUCTOR™		
DRAWN	L. England	9-28-09	4BALL WLCSP, 2X2 ARRAY 0.5MM PITCH, 300UM BALL		
DFTG. CHK.	S. Martin	9-28-09			
ENGR. CHK.					
PROJECTION			SCALE	SIZE	DRAWING NUMBER
INCH [MM]			N/A	N/A	MKT-UC04AB
			DO NOT SCALE DRAWING		REV 2
			SHEET 1 of 1		